

#### **Overview**

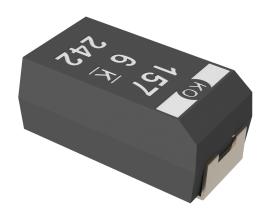
The KEMET Organic Capacitor (KO-CAP) is a solid electrolytic capacitor with a conductive polymer cathode capable of delivering very low ESR and improved capacitance retention at high frequencies. KO-CAP combines the low ESR of multilayer ceramic, the high capacitance of aluminum electrolytic and the volumetric efficiency of tantalum into a single surface mount package. Unlike liquid electrolyte-based capacitors, KO-CAP has a very long operational life and high ripple current capabilities.

# KOCAP Polymer Capacitors

The T522 Reduced Leakage Polymer Electrolytic design is based on the T520 KO-CAP series. Developed specifically to meet the needs of leakage current sensitive applications, the T522 is well-suited for battery-based circuits. The T522 provides the lowest leakage values available in polymer electrolytic capacitors with upper leakage limits that are up to 70% lower than comparable KO-CAP capacitors.

### **Benefits**

- + ESR: 25 to 40 m $\Omega$
- · Volumetrically efficient
- · High frequency capacitance retention
- 100% accelerated steady state aging
- 100% surge current tested
- EIA standard case sizes
- · Low profile designs
- Halogen-free Epoxy/RoHS Compliant



## **Applications**

Typical applications include battery-dependent applications such as handheld consumer electronics, global tracking systems, energy harvesting, wireless sensors and other applications that seek high capacitance, low profile, safety and low power consumption.

### **Environmental Compliance**

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.



#### K-SIM

For a detailed analysis of specific part numbers, please visit ksim.kemet.com to access KEMET's K-SIM software. KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels.

## **Ordering Information**

т	522	V	157	М	006	Α	Т	E025	
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Failure Rate/ Design	Termination Finish	ESR Code	Packaging (C-Spec)
T = Tantalum	522 = Reduced Leakage Polymer	V Y	First two digits represent significant figures. Third digit specifies number of zeros.	M = ±20%	006 = 6.3	A = N/A	T = 100% Matte Tin (Sn) plated H = Tin/Lead (SnPb) solder coated (5% Pb minimum)	E = ESR Last three digits specify ESR in $m\Omega$ . (025 = 25 $m\Omega$ )	Blank = 7" Reel 7280 = 13" Reel

## **Performance Characteristics**

Item	Performance Characteristics
Operating Temperature	-55°C to 105°C
Rated Capacitance Range	150 – 470 uF at 120 Hz/25°C
Capacitance Tolerance	M Tolerance (20%)
Rated Voltage Range	6.3 V
DF (120 Hz)	≤ 10%
ESR (100 kHz)	Refer to Part Number Electrical Specification Table 1
Leakage Current	$\leq$ 0.03 CV (µA) at rated voltage after 10 minutes



# Qualification

Test	Condition			Charact	eristics		
			ΔC/C	Within -20/	+10% of initial	value	
Endurance	105°C at rated valtage 2,000 hours		DF	Within initial limits			
Endurance	105°C at rated voltage, 2,000 hours		DCL	Within 1.5 x initial limit			
			ESR	Within 2.0 x	initial limit		
			ΔC/C	Within -20/	+10% of initial	value	
Storogo Lifo	105°C at 0 volts, 2,000 hours		DF	Within initia	al limits		
Storage Life			DCL	Within 1.5 x	initial limit		
			ESR	Within 2.0 x	initial limit		
			ΔC/C	Within -5%/+35% of initial value			
Humidity	60°C, 90% RH, 500 hours, rated voltage		DF	Within initial limits			
Humidity	ou c, 90% km, 500 hours, fated voltage		DCL	Within 5.0 x	initial limit		
			ESR	Within 2.0 x initial limit			
			+25°C	-55°C	+85°C	+105°C	
Temperature Stability	Extreme temperature exposure at a succession of continuous steps at +25°C,	ΔC/C	IL*	±20%	±20%	±30%	
Temperature Stability	-55°C, +25°C, +85°C, +105°/125°C, +25°C	DF	IL	IL	1.2 x IL	1.5 x IL	
		DCL	IL	N/A	10 x IL	10 x IL	
			ΔC/C	Within -20%	%/+10% of initi	al value	
Surge Voltage	105°C, 1.32 x rated voltage, 33 Ω Resistance	e, 1,000	DF	Within initia	al limits		
Surge voltage	cycles		DCL	Within initial limits			
			ESR	Within initial limits			
	MIL-STD-202, Method 213, Condition I, 100	G peak.	ΔC/C	Within ±10%	6 of initial valu	e	
Mechanical Shock/ Vibration	MIL-STD-202, Method 204, Condition D, 10	DF	Within initia	Within initial limits			
	2,000 Hz, 20 G peak		DCL	Within initia	al limits		

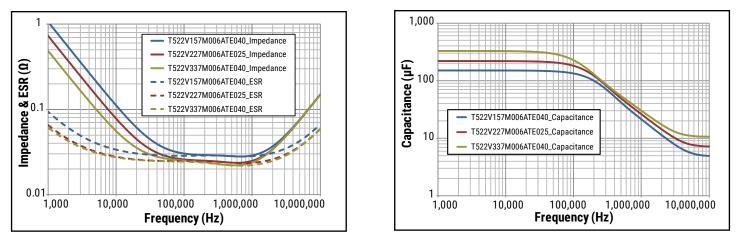
\*IL = Initial limit



## **Electrical Characteristics**

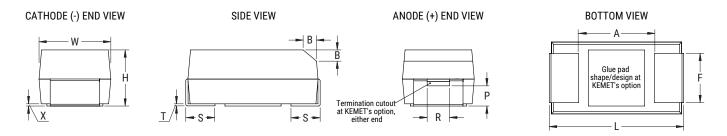
#### Impedance & ESR vs. Frequency





## **Dimensions – Millimeters (Inches)**

Metric will govern



Case	Size		Component Dimensions												
KEMET	EIA	L	W	Н	F ±0.1 ±(0.004)	S ±0.3 ±(0.012)	B ±0.15 (Ref) ±0.006	X (Ref)	P (Ref)	R (Ref)	T (Ref)	A (Minimum)	(mg)		
v	7343-19	7.3±0.3 (0.287±0.012)	4.3±0.3 (0.169±0.012)	1.9 (0.075) ±0.1 (0.004)	2.4 (0.094)	1.3 (0.051)	N/A	0.05 (0.002)	N/A	N/A	0.13 (0.005)	3.8 (0.150)	274.30		
Y	7343-40	7.3±0.3 (0.287±0.012)	4.3±0.3 (0.169±0.012)	3.8 ±0.2 (0.150 ±0.008)	2.4 (0.094)	1.3 (0.051)	0.5 (0.020)	0.10±0.10 (0.004±0.004)	1.7 (0.067)	1.0 (0.039)	0.13 (0.005)	3.8 (0.150)	493.99		

Notes: (Ref) – Dimensions provided for reference only. For low profile cases, no dimensions are provided for B, P or R because these cases do not have a bevel or a notch.

These weights are provided as reference. If exact weights are needed, please contact your KEMET Sales Representative.



Table 1 – Ratings & Part Number Refere
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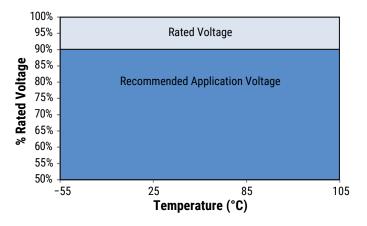
Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR	Maximum Allowable Ripple Current	MSL	Maximum Operating Temp
VDC at 105°C	μF	KEMET/EIA	(See below for part options)	µA at +25°C Max/10 Min.	% at +25°C 120 Hz Max	mΩ at +25°C 100 kHz Max	mA at +45°C 100 kHz	Reflow Temp ≤ 260°C	°C
6.3	150	V/7343-19	T522V157M006A(1)E025	28	10	25	2700	3	105
6.3	150	V/7343-19	T522V157M006A(1)E040	28	10	40	2200	3	105
6.3	220	V/7343-19	T522V227M006A(1)E025	42	10	25	2700	3	105
6.3	220	V/7343-19	T522V227M006A(1)E040	42	10	40	2200	3	105
6.3	330	V/7343-19	T522V337M006A(1)E040	62	10	40	2200	3	105
6.3	470	Y/7343-40	T522Y477M006A(1)E035	89	10	35	2600	3	105

(1) Standard with tin terminations (14th character = T). Tin/lead terminations is also available (14th character = H).

Also available on large (13 inch) reels. Add 7280 to the end of the part number.

Higher voltage ratings and tighter tolerance product including ESR may be substituted within the same size at KEMET's option. Voltage substitutions will be marked with the higher voltage rating. Substitutions can include better than series.

## **Derating Guidelines**



#### **Recommended Application Voltage**

KOCAP's are solid state capacitors that demonstrate no wearout mechanism when operated within their recommended guidelines.While the KOCAP can be operated at full rated voltage, most circuit designers seek a minimum level of assurance in long term reliability which should be demonstrated with data.

A voltage derating can provide the desired level of demonstrated reliability based on industry accepted acceleration models. Since most applications do require long term reliability, KEMET recommends that designers consider a voltage derating, according the graphic above, for the maximum steady state voltage.

Voltage Rating	Maximum Recommended Steady State Voltage
	-55°C to 105°C
6.3 V	90% of V <sub>R</sub>

 $V_{R}$  = Rated Voltage



## **Ripple Current/Ripple Voltage**

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.

2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

· · · · · · · · · · · · · · · · · · ·	ure Compensation M Maximum Ripple Cu	· · · · ·
T ≤ 45°C	45° C < T ≤ 85°C	85°C < T ≤ 125°C
1.00	0.70	0.25

T= Environmental Temperature

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

KEMET Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts at 45°C with +30°C Rise
V	7343-19	187
Y	7343-40	241

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P max/R}$  $E(max) = Z \sqrt{P max/R}$ 

*I = rms ripple current (amperes)* 

E = rms ripple voltage (volts)

*P* max = maximum power dissipation (watts)

*R* = *ESR* at specified frequency (ohms)

*Z* = *Impedance at specified frequency (ohms)* 



## Surge Voltage

Surge voltage is the maximum voltage (peak value) which may be applied to the capacitor.

The surge voltage must not be applied for periodic charging and discharging in the course of normal operation and cannot be part of the application voltage.

Surge voltage capability is demonstrated by application of 1,000cycles at relevant voltage at 105°C and 125°C.

The parts are charged through a 33 Ohm resistor for 30 seconds and then discharged though a 33 Ohm resistor for each cycle.

Rated Voltage (V)	Surge Voltage (V)	Derated Voltage (V)	Derated Surge Voltage (V)				
−55°C t	o 105°C	Up to	125°C				
2, 5	3, 3	1, 7	2, 2				
6, 3	8, 2	4, 2	5, 5				
10	13, 0	6, 7	8, 7				
16	20, 8	10, 7	13, 9				
20	26, 0	13, 4	17, 4				
25	32, 5	16, 8	21, 8				
35	45, 5	23, 5	30, 5				
50	65,	33, 5	43, 6				

## **Reverse Voltage**

Polymer electrolytic capacitors are polar devices and may be permanently damaged or destroyed if connected in the wrong polarity. These devices will withstand a small degree of transient voltage reversal for short periods as shown in the below table.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of rated voltage
55°C	10% of rated voltage
85°C	5% of rated voltage
105°C	3% of rated voltage
125°C*	1% of rated voltage

\*For series rated to 125°C



## Table 2 – Land Dimensions/Courtyard

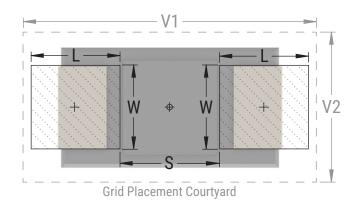
KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)			Density Level B: Median (Nominal) Land Protrusion (mm)				Density Level C: Minimum (Least) Land Protrusion (mm)							
Case	EIA	W	L	S	V1	V2	W	L	S	V1	V2	W	L	S	V1	V2
V	7343-20	2.55	2.77	3.67	10.22	5.60	2.43	2.37	3.87	9.12	5.10	2.33	1.99	4.03	8.26	4.84
<b>Y</b> <sup>1</sup>	7343-40	2.55	2.77	3.67	10.22	5.60	2.43	2.43 2.37 3.87 9.12 5.10				2.33 1.99 4.03 8.26 4.84				

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component desity product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC standard 7351 (IPC-7351).

 $^{\scriptscriptstyle 1}$  Height of these chips may create problems in wave soldering.

<sup>2</sup> Land pattern geometry is too small for silkscreen outline.





## **Soldering Process**

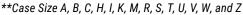
KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

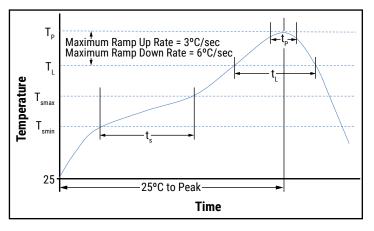
Please note that although the X/7343-43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

Profile Feature	SnPb Assembly	Pb-Free Assembly	
Preheat/Soak			
Temperature Minimum $(T_{smin})$	100°C	150°C	
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C	
Time ( $t_s$ ) from $T_{min}$ to $T_{max}$ )	60 – 120 seconds	60 – 120 seconds	
Ramp-up Rate ( $T_L$ to $T_P$ )	3°C/seconds maximum	3°C/seconds maximum	
Liquidous Temperature $(T_L)$	183°C	217°C	
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds	
Peak Temperature (T <sub>P</sub> )	220°C* 235°C**	250°C* 260°C**	
Time within 5°C of Maximum Peak Temperature (t <sub>P</sub> )	20 seconds maximum	30 seconds maximum	
Ramp-down Rate $(T_{P} to T_{L})$	6°C/seconds maximum	6°C/seconds maximum	
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum	

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow. \*Case Size D, E, P, Y, and X



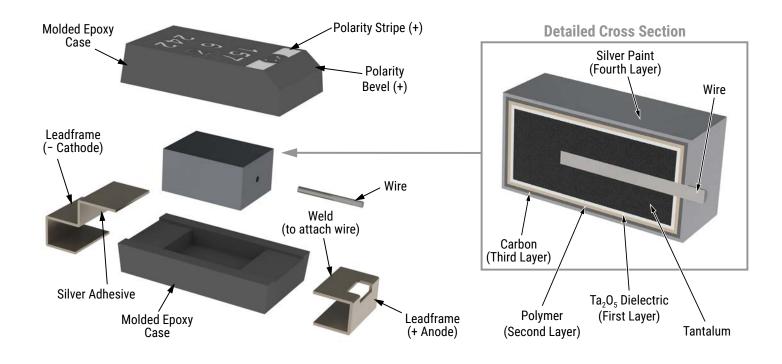


#### Storage

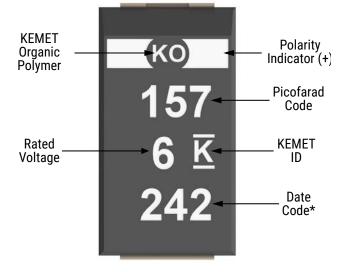
All KO-CAP Series are shipped in moisture barrier bags with a desiccant and moisture indicator card. This series is classified as MSL3 (Moisture Sensitivity Level 3). Product contained within the moisture barrier bags should be stored in normal working environments with temperatures not to exceed 40°C and humidity not in excess of 90% RH.



## Construction



**Capacitor Marking** 



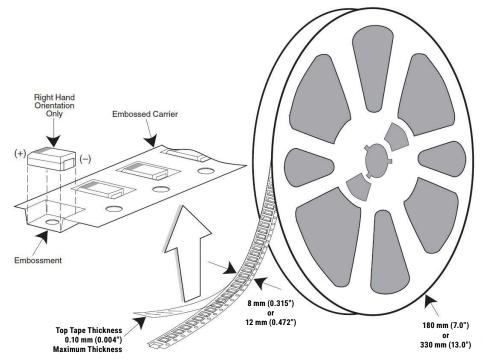
Date Code *					
1st digit = Last number of Year	2 = 2012 3 = 2013 4 = 2014 5 = 2015 6 = 2016 7 = 2017				
2 <sup>nd</sup> and 3 <sup>rd</sup> digit = Week of the Year	01 = $1^{st}$ week of the Year to 52 = $52^{nd}$ week of the Year				

\* 242 = 42<sup>nd</sup> week of 2012



### **Tape & Reel Packaging Information**

KEMET's molded chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.



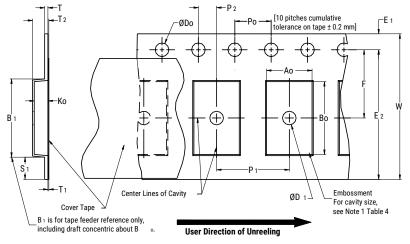
## Table 3 – Packaging Quantity

Case Code		Tape Width (mm)	7" Reel*	13" Reel*	
KEMET	EIA				
R	2012-12	8	2,500	10,000	
I	3216-10	8	3,000	12,000	
S	3216-12	8	2,500	10,000	
Т	3528-12	8	2,500	10,000	
М	3528-15	8	2,000	8,000	
U	6032-15	12	1,000	5,000	
L	6032-19	12	1,000	3,000	
W	7343-15	12	1,000	3,000	
Z	7343-17	12	1,000	3,000	
V	7343-19	12	1,000	3,000	
А	3216-18	8	2,000	9,000	
В	3528-21	8	2,000	8,000	
С	6032-28	12	500	3,000	
D	7343-31	12	500	2,500	
Y	7343-40	12	500	2,000	
Х	7343-43	12	500	2,000	
E/T428P	7360-38	12	500	2,000	
Н	7360-20	12	1,000	2,500	

\* No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.



## Figure 1 – Embossed (Plastic) Carrier Tape Dimensions



## Table 4 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm		1.0 (0.039)			2.0±0.05	25.0 (0.984)			
12 mm	1.5+0.10/-0.0 (0.059+0.004/-0.0)	1.5	1.75±0.10 (0.069±0.004)	4.0±0.10 (0.157±0.004)	(0.079±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm		(0.059)	()	(	2.0±0.1 (0.079±0.059)	(1.181)	()	()	

	Variable Dimensions – Millimeters (Inches)								
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5±0.05 (0.138±0.002)	2.0±0.05 or 4.0±0.10 (0.079±0.002 or 0.157±0.004)	2.5 (0.098)	8.3 (0.327)		
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5±0.05 (0.217±0.002)	2.0±0.05 (0.079±0.002) or 4.0±0.10 (0.157±0.004) or 8.0 ±0.10 (0.315±0.004)	4.6 (0.181)	12.3 (0.484)	Note 5	
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5±0.10 (0.295±0.004)	4.0±0.10 (0.157±0.004) to 12.0±0.10 (0.472±0.004)	8.0 (0.315)	16.3 (0.642)		

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.

2. The tape, with or without components, shall pass around R without damage (see Figure 4).

3. If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).

4. B, dimension is a reference dimension for tape feeder clearance only.

5. The cavity defined by  $A_{qr} B_{q}$  and  $K_{q}$  shall surround the component with sufficient clearance that:

(a) the component does not protrude above the top surface of the carrier tape.

(b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

(c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).

(d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).

(e) see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.



### **Packaging Information Performance Notes**

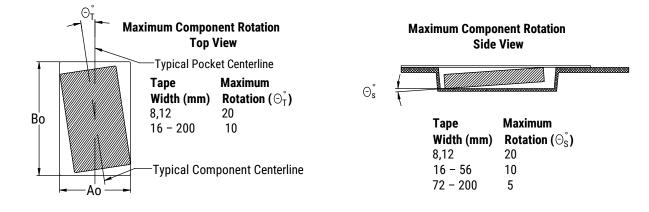
- 1. Cover Tape Break Force: 1.0 Kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300±10 mm/minute.

**3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

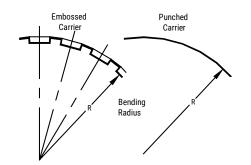
### Figure 2 – Maximum Component Rotation



## Figure 3 – Maximum Lateral Movement

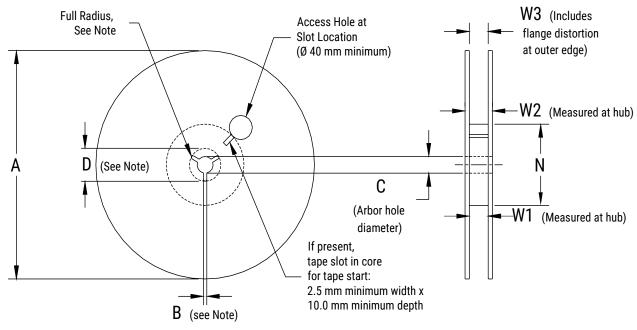


## Figure 4 – Bending Radius





## **Figure 5 – Reel Dimensions**



Note: Drive spokes optional; if used, dimensions B and D shall apply.

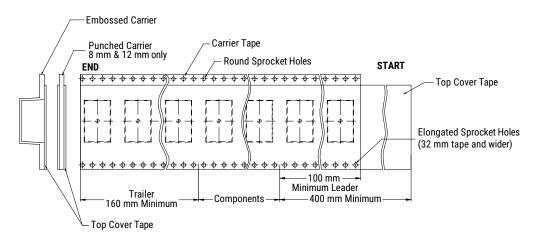
## **Table 5 – Reel Dimensions**

Metric will govern

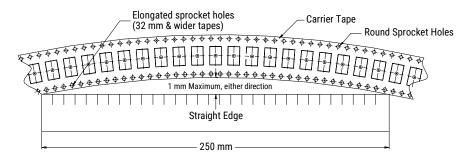
Constant Dimensions – Millimeters (Inches)							
Tape Size	А	B Minimum C		D Minimum			
8 mm	178±0.20		13.0+0.5/-0.2 (0.521+0.02/-0.008)				
12 mm	(7.008±0.008) or	1.5 (0.059)		20.2 (0.795)			
16 mm	330±0.20 (13.000±0.008)			× /			
	Variable Dimensions – Millimeters (Inches)						
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>			
8 mm		8.4+1.5/-0.0 (0.331+0.059/-0.0)	14.4 (0.567)				
12 mm	50 (1.969)	12.4+2.0/-0.0 (0.488+0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference			
16 mm		16.4+2.0/-0.0 (0.646+0.078/-0.0)	22.4 (0.882)	_			



## Figure 6 – Tape Leader & Trailer Dimensions



# Figure 7 – Maximum Camber





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